

TDA4482-D

Quasi-Parallel Sound Processor for TV Sets

Technology: Bipolar

Features

- High signal sensitivity
- Simple filter configuration and few external components
- Processing of two carrier stereo signals
- ESD protected
- Low intercarrier distortions

- Alignment-free intercarrier mixer
- Optimum tuning characteristics
- Improved linearity for NICAM applications
- AF output level matched to SIMAVELEC condition

Case: DIP18

Block Diagram

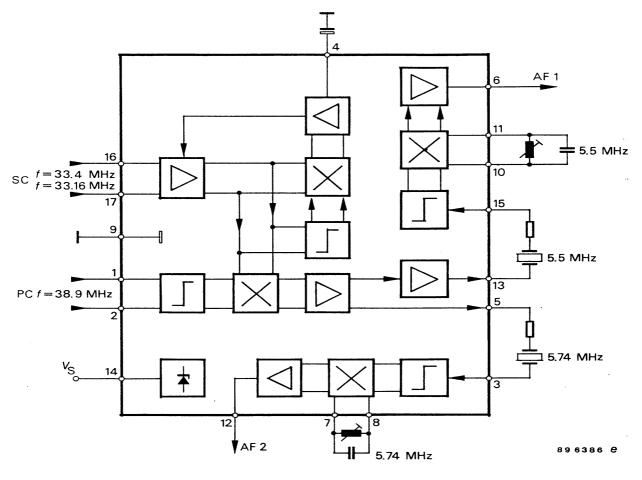


Figure 1.

Pin Configuration

Pin	Function
1-2	Vision-IF-carrier input
3	Intercarrier input 5.74 MHz
4	AGC storage capacitor
5	Intercarrier output 5.74 MHz
6	AF output 1
7–8	FM demod circuit 5.74 MHz
9	Ground

Pin	Function
10–11	FM-demode circuit 5.5 MHz
12	AF output 2
13	Intercarrier output 5.5 MHz
14	Supply voltage
15	Intercarrier input 5.5 MHz
16–17	Sound-IF-carrier input
18	Not conneccted

Circuit Description

This circuit configuration permits high-quality processing of audio carriers for FM-sound standards, providing separate inputs for the video and audio carrier. The audio carrier signal is passed to two multiplying mixer arrangements via a 3-stage variable wideband amplifier with led level output signals. One mixer generates the gain-control signal. The second mixer operates as an intercarrier demodulator and supplies the intermediate AF carrier. The video carrier signal required from the intercarrier is decoupled in a prelimited and selected form from the demodulator tank of the intermediate video frequency circuit (TDA4453 or TDA4439) and led to the intercarrier mixer via a limiting amplifier. Depending on the system, the Nyquist range of the IF input filter in the video channel affects the attainable AF signal-to-noise ratio.

The audio PM IF carrier reaches the quadrature demodulators via an inter-connected IF filter and subsequent limiting amplifier. The resulting AF signals are led via a low-pass amplifier with increased level to the buffered output stages. Switching can take place with TTLequivalent levels.

Absolute Maximum Ratings

Reference point Pin 9, 18, unless otherwise specified

Paramet	Symbol	Value	Unit	
Supply voltage	Pin 14	Vs	10 to 13.5	V
Supply current	Pin 14	IS	80	mA
External voltages Pins 1, 2, 3, 4, 5, 7, 8, 10, 11, 12, 13, 15, 16 and 17		V _{ext}	6	V
Power dissipation (in soldered position)		P _{tot}	1	W
Junction temperature		Tj	125	°C
Ambient temperature range		T _{amb}	-25 to +70	°C
Storage temperature range	T _{stg}	-25 to +125	°C	

Thermal Resistance

Parameters	Symbol	Maximum	Unit
Junction ambient	R _{thJA}	60	K/W

Electrical Characteristics

 $V_S = 12$ V, $T_{amb} = 25^{\circ}$ C, reference point Pin 9, $f_{PC} = 38.9$ MHz, $f_{SC1} = 33.43$ MHz, $f_{SC2} = 33.1578$ MHz, SC1/SC2 = 7 dB, unless otherwise specified

Parameters	Test Conditions / Pin	Symbol	Min	Тур	Max	Unit
Supple voltage range	Pin 14	Vs	10		13.5	V
Supply current	Pin 14	Is	55	62	80	mA
Output dc voltage	Pin 6, 12	V_0		3.6		V
Picture carrier input voltage	Pin 1–2	v	10	20	30	mV
Min. sound carrier input voltage SC1	(5.5 MHz-output signal -3 dB) Pin 16–17	v		50		μV
AGC range			60	65		dB
Audio output voltage	FM deviation = 27 kHz, Pin 6, 12	v		500		mV
Audio-voltage difference between both outputs	Pin 6, 12	Δv_{AF}			1	dB
Harmonic distortion ¹⁾	f _{mod} = 1 kHz, FM deviation = 30 kHz Pin 6, 12	THD		0.5		%
Limiting threshold	$(V_{AF}-3 dB)$			250		μV
AM rejection				55		dB
FM amplifier input resistance		R _{3,15}		560		Ω
Min. output load	Pin 6,12	R	3			kΩ
	d B/G) according to CCIR 468-2 demodulator picture carrier sign			SC1 = 10 m	nV, SC2 = 4	4.5 V
Black burst	1. channel/ 2. channel ^{2,3)} Pin 6,12	(S+N)/N		62/60		dB
Grid test signal	1. channel/ 2. channel ^{2,3)} Pin 6,12	(S+N)/N		50/48		dB

¹⁾ FM tank circuits: operation quality factor = 22

²⁾ Standard B/G IF-modulated FBAS signal

³⁾ Reference signal: $f_{mod} = 1$ kHz, FM deviation = 30 kHz

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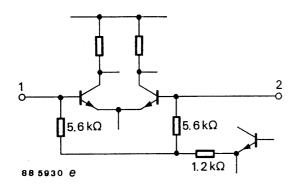


Figure 2. Pin 1, 2: IF input vision carrier

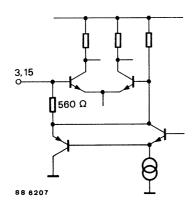


Figure 3. Pin 3 (15): Intercarrier input Pin 3 = 5.74 MHz, Pin 15 = 5.5 MHz

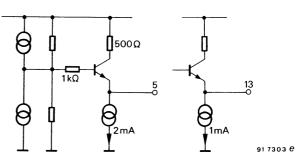


Figure 5. Pin 5 (13): Intercarrier output Pin 5 = 5.74 MHz, Pin 13 = 5.5 MHz

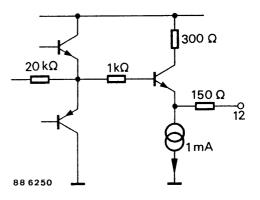


Figure 6. Pin 12: AF output 2

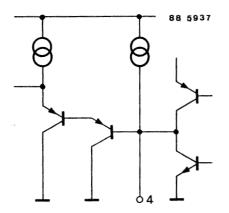


Figure 4. Pin 4: AGC storage capacitor

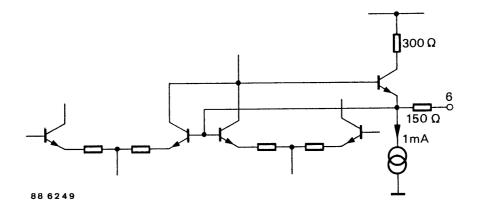


Figure 7. Pin 6: AF output 1

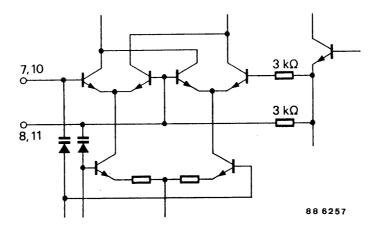


Figure 8. Pin 7, 8 (10, 11) FM demodulator circuit Pin 7,8 = 5.74 MHz, Pin 10, 11 = 5.5 MHz

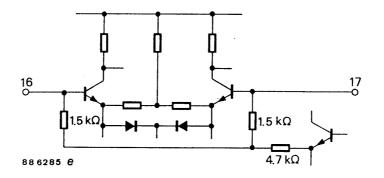
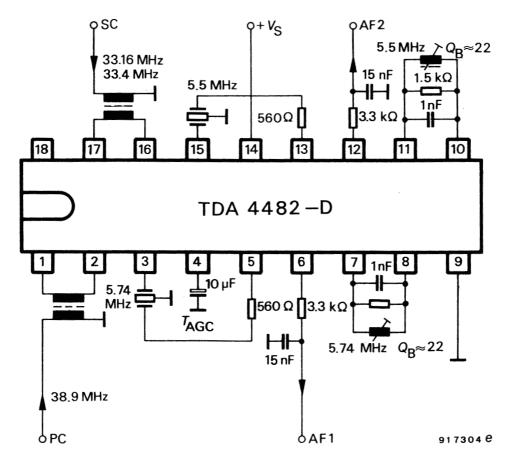


Figure 9. Pin 16, 17: IF input sound carrier

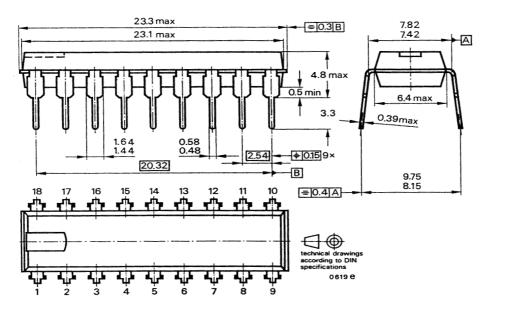
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Test Circuit



Dimensions in mm

Case: 18-Pin dual inline plastic







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- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

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- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

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